

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (canceled).
2. (canceled).
3. (currently amended): A printed wiring substrate comprising:  
a core substrate having a front surface and a back surface; ~~and~~  
an electronic component embedded in said core substrate;  
~~said printed wiring substrate characterized in that:~~  
said electronic component ~~has~~ having an electrode having a height projecting from at  
least ~~either an upper end or a lower end~~ thereof; ~~and~~  
a dielectric layer covering the front surface of the core substrate;  
terminal electrodes for mounting a semiconductor element on the front surface of the  
printed wiring substrate; and  
via holes penetrating the insulating layer and connecting at least one of the terminal  
electrodes to the electrode of the electronic component,  
wherein said core substrate or a resin embedding the electronic component in the core  
substrate contains an inorganic filler.

4. (previously presented): The printed wiring substrate as claimed in claim 13, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

5. (previously presented): The printed wiring substrate as claimed in claim 14, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

6. (original): The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

7. (previously presented): The printed wiring substrate as claimed in claim 13, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

8. (previously presented): The printed wiring substrate as claimed in claim 14, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

9. (original): The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

10. (original): The printed wiring substrate as claimed in claim 4, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

11. (currently amended): A method for manufacturing a printed wiring substrate comprising a core substrate having a front surface and a back surface;

an electronic component embedded in said core substrate via a resin in a through-hole extending through said core substrate between the front surface and the back surface of the core substrate,

said electronic component having an electrode having a height projecting from at least an upper end thereof;

a dielectric layer covering the front surface of the core substrate;

terminal electrodes for mounting a semiconductor element on the front surface of the printed wiring substrate; and

via conductors penetrating the insulating layer and connecting at least one of the terminal electrodes to the electrode of the electronic component,

wherein said resin embedding the electronic component in the core substrate contains an inorganic filler, ~~a core substrate having a front surface and a back surface and an electronic component embedded via a resin in a through hole extending through the core substrate between the front surface and back surface of the core substrate,~~

said method comprising the steps of:

inserting into the through-hole the electronic component having an electrode projecting from at least ~~either an upper end or a lower end~~ thereof;

embedding the electronic component in the through-hole by means of a resin containing an inorganic filler; and

polishing a surface of the resin so as to expose an end surface of the electrode.

12. (currently amended): A method for manufacturing a printed wiring substrate comprising a core substrate having a front surface and a back surface;

an electronic component embedded in said core substrate via a resin in a recess formed in said core substrate and extending from an interior of said core substrate to the front surface or back surface of the core substrate,

said electronic component having an electrode having a height projecting from at least an upper end thereof;

a dielectric layer covering the front surface of the core substrate;

terminal electrodes for mounting a semiconductor element on the front surface of the printed wiring substrate; and

via conductors penetrating the insulating layer and connecting at least one of the terminal electrodes to the electrode of the electronic component,

wherein said resin embedding the electric component in the core substrate contains an inorganic filler, a core substrate having a front surface and a back surface and an electronic

~~component embedded via a resin in a recess formed in the core substrate and extending from an interior of the core substrate to the front surface or the back surface,~~

said method comprising the steps of:

inserting into the through-hole or the recess the electronic component having an electrode projecting from at least ~~either an upper end or a lower end~~ thereof;

embedding the electronic component in the recess by means of a resin containing an inorganic filler; and

polishing a surface of the resin so as to expose an end surface of the electrode.

13. (previously presented): The printed wiring substrate as claimed in claim 3, wherein said electronic component is embedded in the core substrate via a resin in a through-hole extending through said core substrate between the front surface and the back surface of the core substrate, and the resin contains said inorganic filler.

14. (previously presented): The printed wiring substrate as claimed in claim 3, wherein said electronic component is embedded in the core substrate via a resin in a recess formed in said core substrate and extending from an interior of said core substrate to the front surface or back surface of the core substrate, and the resin contains said inorganic filler.